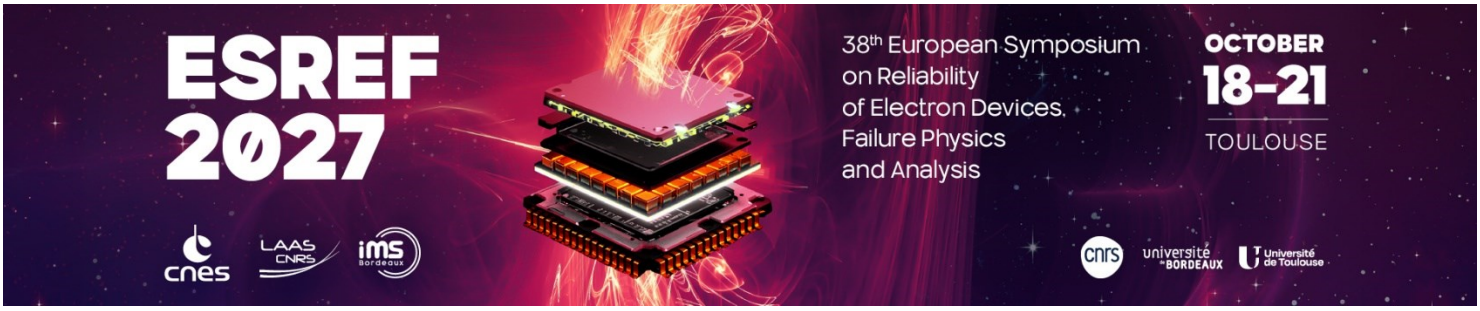


CALL FOR PAPERS

ESREF 2027, the 38th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis, will take place in Toulouse (France) from 18th to 21th October 2027 at *DIAGORA Congress Center*.

This international symposium continues to focus on recent developments and future directions in Quality and Reliability Management of materials, devices and circuits for micro-, nano-, and optoelectronics. It provides a European forum for developing all aspects of reliability management and innovative analysis techniques for present and future electronic applications.

A word from the conference chairs

ESREF 2027 will be held in Toulouse - world center for aeronautics with Airbus assembly line, European capital of the space industry and leader in France for embedded electronic systems. Toulouse, called "Ville rose" (Pink city) for its characteristic architecture based on terra-cotta bricks, combines a strong living spirit with a brilliant past. It is the third French university with more than 120,000 students and 140 Laboratories. It is definitely turned towards the future with a large number of cutting-edge businesses in aeronautics, information technologies and spatial industries, as well as many research institutes. Hosting ESREF 2027 in this rich environment is a great opportunity since reliability in these particular applications is a very hot topic with strong challenges such as zero ppm failure and harsh environments. In the continuity of previous conferences, ESREF 2027 is also hosting several workshops and welcomes new ones related to these specific topics.

We are looking forward to welcoming you to a memorable experience!

Guillaume BASCOUL
ESREF 2027 General Chair

Nicolas NOLHIER
ESREF 2027 Vice-Chair

Technical Program Chairs : Alexandrine GRACIA, Nathalie LABAT, François MARC, Nicolas NOLHIER, Loïc THEOLIER

with the technical co-sponsorship of The French FA Society

DEADLINES

1 February 2027	**Submission opening of four-page summary to be uploaded at: http://www.esref2027.org**
8 March 2027	**Submission deadline.**
30 April 2027	**Notification of acceptance of paper for conference proceeding (Oral or Poster).** **A selection of paper will also be eligible for publication in a special issue of a journal in an extended version (>30%).**
11 June 2027	**Submission deadline of extended papers in the online Journal Editorial System.**
18 June 2027	**Upload deadline of the proceeding's final version.**
After ESREF 2027	**Publication of the extended paper in the journal.**

SCOPE OF PAPERS

Papers are requested on the following topics:

A - Quality and Reliability assessment techniques and methods for Devices and Systems

B - Semiconductor Failure Mechanisms & Reliability for Si technologies & Nanoelectronics

C - Progress in Failure Analysis: Defect Detection and Analysis

D - Reliability of Microwave devices and circuits

E - Packaging and Assembly Reliability and Failure Analysis

F - Power Devices and Microelectronic System: Reliability and Failure Analysis

- F1 : Smart-power devices, Silicon Power Devices,
- F2 : Wide Band-gap devices
- F3 : Power Electronic System

G - Photonics Reliability

H - MEMS and sensors Reliability

I - Extreme environments and Radiation

CONFERENCE CONTENT

Tutorials by experts will provide review presentation of relevant topics and **Invited papers** will introduce the mainstream topics.

Workshops organized in partnership with the ESREF conference will give us the opportunity to exchange the know-how and field returns on specific topics.

Exhibition - The Symposium will feature the latest in-service providers, equipment manufacturers and suppliers in these fields.

Sponsor - Get advantages of sponsor packages (platinum, gold and silver).

For further information about exhibition and sponsoring, please contact the administrative team : sponsors@esref2027.org

Conference Website : **http://www.esref2027.org** / *Contact :* **contact@esref2027.org**